



Dual P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)		
- 20	0.037 at $V_{GS} = -4.5 \text{ V}$	- 7.4		
	0.048 at V _{GS} = - 2.5 V	- 6.5		
	0.066 at V _{GS} = - 1.8 V	- 55		

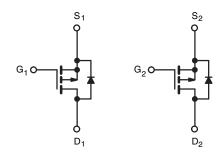
FEATURES

- TrenchFET® Power MOSFET
- New Low Thermal Resistance PowerPAK® Package



APPLICATIONS

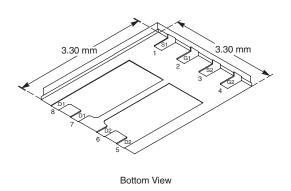
- Portable
 - PA Switch
 - Battery Switch
 - Load Switch



P-Channel MOSFET

P-Channel MOSFET

PowerPAK 1212-8



Ordering Information: Si7913DN-T1-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise r	noted			
Parameter		Symbol	10 sec	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 20		V	
Gate-Source Voltage		V _{GS}	± 8			
Continuo Dunio Comment /T 150 00\8	T _A = 25 °C	1	- 7.4	- 5.0	^	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 85 °C	I _D	- 5.3	- 3.6		
Pulsed Drain Current		I _{DM}	- 20		Α	
Continuous Source Current (Diode Conduction) ^a		I _S	- 2.3	- 1.1		
	T _A = 25 °C	В	2.8	1.3	14/	
Maximum Power Dissipation ^a	T _A = 85 °C	- P _D	1.5	0.85	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		00	
Soldering Recommendations (Peak Temperature)b, c			260		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	- R _{thJA}	35	44	°C/W	
	Steady State		75	94		
Maximum Junction-to-Case	Steady State		4	5		

a. Surface Mounted on 1" x 1" FR4 Board.
b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

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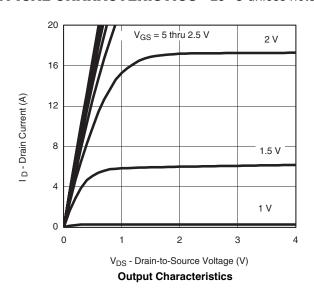


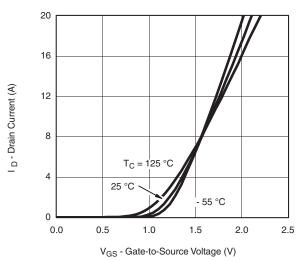
SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.40		- 1.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1		
		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 85 °C			- 5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α	
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 7.4 A		0.029	0.037	0.048 Ω	
		V _{GS} = - 2.5 V, I _D = - 6.5 A		0.038	0.048		
		V _{GS} = - 1.8 V, I _D = - 1.5 A		0.051	0.066		
Forward Transconductance ^a	9 _{fs}	V _{DS} = -6 V, I _D = -7.4 A		20		S	
Diode Forward Voltage ^a	V _{SD}	I _S = - 2.3 A, V _{GS} = 0 V		- 0.74	- 1.2	V	
Dynamic ^b							
Total Gate Charge	Q_g			15.3	24		
Gate-Source Charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.4 \text{ A}$		2.0		nC	
Gate-Drain Charge	Q_{gd}			3.9			
Gate Resistance	R_g	f = 1 MHz		7		Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 10 \Omega$		70	110		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 6 Ω		72	110	ns	
Fall Time	t _f			150	225		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 2.3 A, di/dt = 100 A/μs		25	50		

Notes: a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C unless noted





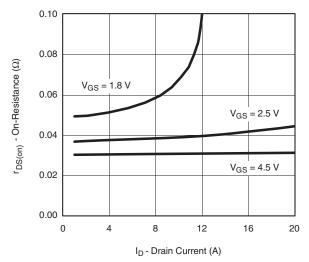
Transfer Characteristics



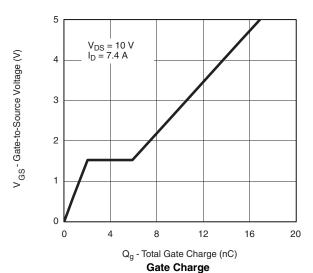


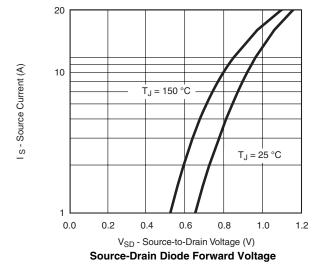


TYPICAL CHARACTERISTICS 25 °C unless noted



On-Resistance vs. Drain Current

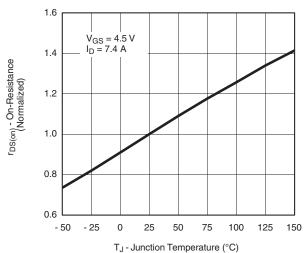




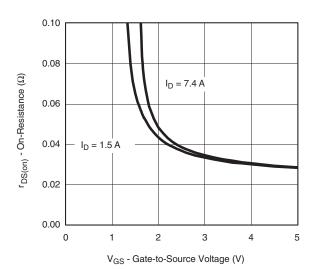
2100 1800 1500 C - Capacitance (pF) C_{iss} 1200 900 600 Coss 300 C_{rss} 0 0 4 8 12 20 16

V_{DS} - Drain-to-Source Voltage (V)

Capacitance



On-Resistance vs. Junction Temperature

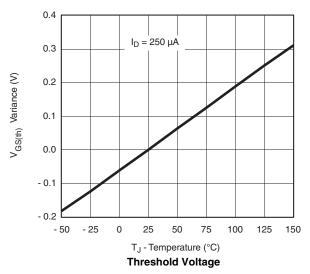


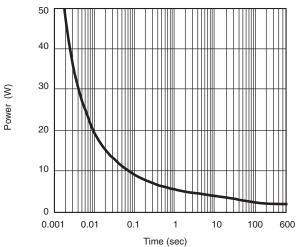
On-Resistance vs. Gate-to-Source Voltage

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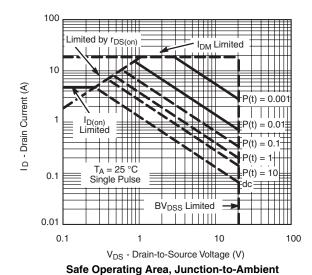
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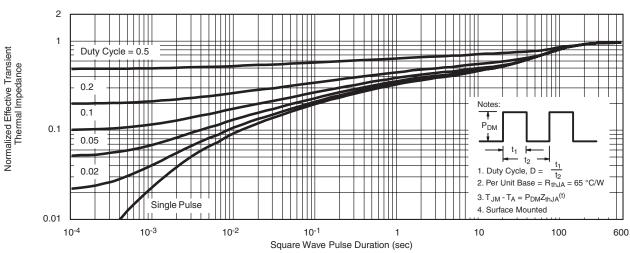
TYPICAL CHARACTERISTICS 25 °C unless noted





Single Pulse Power, Junction-to-Ambient

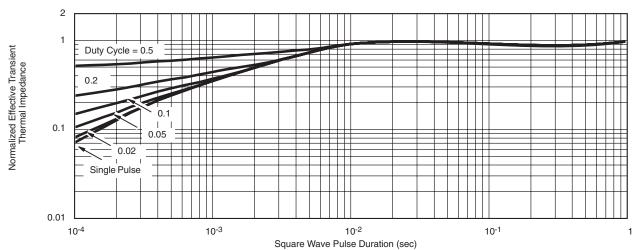




Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C unless noted



Normalized Thermal Transient Impedance, Junction-to-Case

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